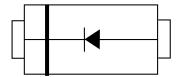






Feature

- For surface mounted applications
- Low profile package
- Glass Passivated Chip Juntion
- > Superfast reverse recovery time
- ➤ Lead free in comply with EU RoHS 2011/65/EU directives



Mechanical Characteristics

Case: SMAF

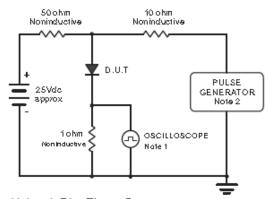
> Terminals: Solderable per MIL-STD-750, Method 2026

Approx. Weight: 27mg 0.00086oz

Absolute maximum rating@25℃

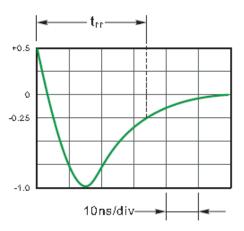
Parameter	Symbol	PES1	PES1 BF	PES1 CF	PES1	PES1 EF	PES1 GF	PES1 JF	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	50	100	150	200	300	400	600	V
Maximum RMS voltage	V _{RMS}	35	70	105	140	210	280	420	V
Maximum DC Blocking Voltage	V _{DC}	50	100	150	200	300	400	600	V
Maximum Average Forward Rectified Current at Ta =100 °C	I _{F(AV)}	1						Α	
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	IFSM	30					Α		
Maximum Forward Voltage at 1 A	VF	1 1.25 1.7			1.7	V			
Maximum DC Reverse Current Ta=25 °C at Rated DC Blocking Voltage Ta=125 °C	I _R	5 100					μΑ		
Typical Junction Capacitance at V _R =4V, f=1MHz	Cj	10					pF		
Maximum Reverse Recovery Time at I _F =0.5A, I _R =1A, I _{rr} =0.25A	t _{rr}	35					nS		
Operating and Storage Temperature Range	Tj, Tstg	-55 ~ +150				°C			

Typical Characteristics



Note: 1. Rise Time = 7ns, max. Input Impedance = 1megohm,22pF.

2. Ries Time = 10ns, max. Source Impedance = 50 ohms.



Set time Base for 10ns/div

Fig. 1 Reverse Recovery Time Characteristic And Test Circuit Diagram

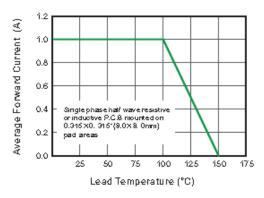


Fig. 2 Meximum Average Forward Current Rating

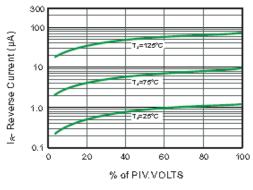


Fig.3 Typical Reverse Characteristics

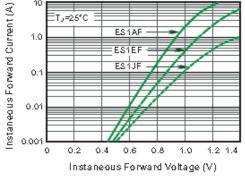


Fig.4 Typical Forward Characteristics

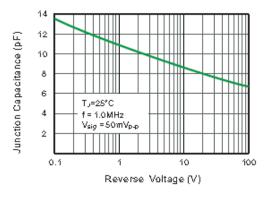
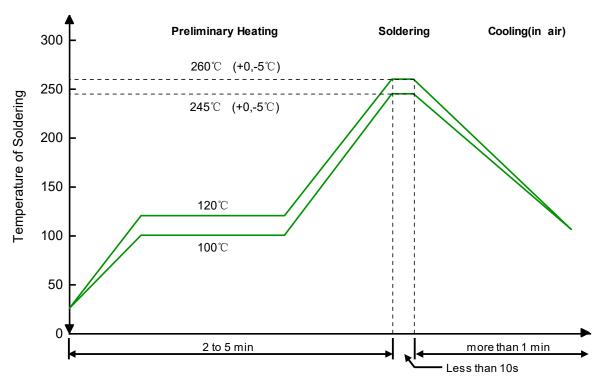


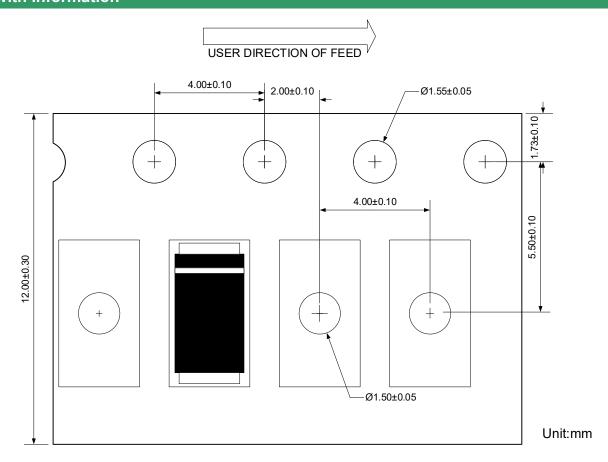
Fig.5 Typical Junction Capacitance

Solder Reflow Recommendation

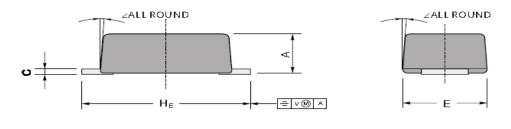


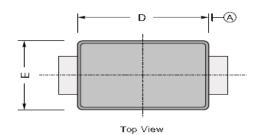
Remark: Pb free for 260°C; Pb for 245°C.

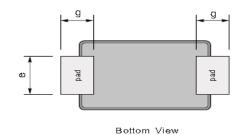
Load with information



Product dimension (SMAF)

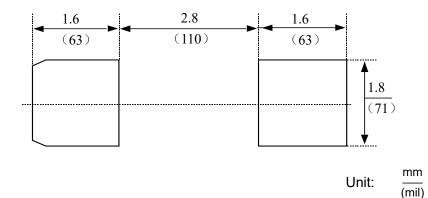






UNIT		Α	С	D	E	е	g	HE	_
mm	max	1.2	0.20	3.7	2.7	1.6	1.2	4.9	7°
	min	0.9	0.12	3.3	2.4	1.3	0.8	4.4	
mil	max	47	7.9	146	106	63	47	193	/
	min	35	4.7	130	94	51	31	173	

The recommended mounting pad size



Ordering information

Device	Package	Shipping			
PES1AF-PES1JF	SMAF (Pb-Free)	3000/ Tape & Reel			

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